PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Ching-Chung SU	12/11/2007
Yi-Wei CHIU	12/11/2007
Tzu-Chan WENG	12/11/2007
Yih Song CHIU	12/11/2007
Pin Chia SU	12/11/2007
Chih-Cherng JENG	12/11/2007
Kuo-Hsiu WEI	12/11/2007

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11958942

CORRESPONDENCE DATA

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CH $40.00 11958942

ATTORNEY DOCKET NUMBER:	24061.974
NAME OF SUBMITTER:	David M. O'Dell
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ASSIGNMENT

WHEREAS, we,

(1) Ching-Chung Su of No. 92, Lane 209, Jhongjheng Rd.
Yongkang City, Tainan County, Taiwan, R.O.C.

(2) Yi-Wei Chiu of Bao Yang Street, No. 343
Kaohsiung, Taiwan, R.O.C.

(3) Tzu-Chan Weng of 8F, No. 512, Guangsi Rd, Cianjhen District
Kaohsiung City 806, Taiwan, R.O.C.

(4) Yih Song Chiu of 29, Da-Ming Rd., Chu-Tung
Hsin-Chu, Taiwan, R.O.C.

(5) Pin Chia Su of No. 31, Hucuoliao, Shanhua Township
Tainan County 741, Taiwan, R.O.C.

(6) Chih-Cherng Jeng of 8F, 6, Lane 2, Sec. 3, JinGuo Rd.
Hsin-Chu City, Tainan County, Taiwan, R.O.C.

(7) Kuo-Hsiu Wei of No. 17, Lane 182, Yude 2nd Rd., North District
Tainan City 704, Taiwan, R.O.C.

have invented certain improvements in

FEATURE DIMENSION MEASUREMENT

for which we have executed an application for Letters Patent of the United States of America,

_______ of even date filed herewith; and
X filed on December 18, 2007 and assigned application no. 11/958,942 and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar ($1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Ching-Chung Su

Residence Address: No. 92, Lane 209, Jhongjheng Rd.
Yongkang City, Tainan County, Taiwan, R.O.C.

Dated: 2007/12/11

Inventor Signature

Inventor Name: Yi-Wei Chiu

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Dated: 2007/12/11

Inventor Signature

Docket No.: 2007-0524 / 24061.974
Customer No.: 42717

Inventor Name: Tzu-Chan Weng

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Dated: 2007/12/11

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Inventor Name: Yih Song Chiu

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Dated: 邱奕松 2007.12/11

邱奕松
Inventor Signature

Inventor Name: Pin Chia Su

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Dated: Dec 11, '07

Pin-Chia, Su
Inventor Signature

Inventor Name: Chih-Cherng Jeng

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Dated: Dec 26 '07

Chih-Cheng Jeng
Inventor Signature

Inventor Name: Kuo-Hsiu Wei

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Dated: 2007. 12. 11

魏國修.
Inventor Signature
